



Bill of Materials

TI DESIGNS
PMP10449

Item	Qty	Reference	Value	Part Description	Manufacturer	Manufacturer Part Number	Alternate Part	PCB Footprint	Note
1	4	TMAC1;TMAC4;TMAC5;TMAC25	0.1UF	CAP, CERAMIC,0.1UF,16V,10%,0402_X7R_PB-FR	Generic	Generic		SM0402	
2	1	TMAC6	1UF	CAP, CERAMIC,1UF,10V,10%,X5R_0402_RG-A	Generic	Generic		SM0402	
3	2	TMAC7;TMAC11	0.22UF	CAP, CERAMIC,0.22UF,10V,10%,0402_X5R_PB-FR	Generic	Generic		SM0402	
4	1	TMAC8	1000PF	CAP, CERAMIC,1000PF,50V,10%,0402_X7R_PB-FR	Generic	Generic		SM0402	
5	1	TMAC9	820PF	CAP, CERAMIC,820PF,25V,5%,0402_NP0	Generic	Generic		SM0402	
6	1	TMAC10	0.022UF	CAP, CERAMIC,0.022UF,16V,10%,0402_X7R_PB-FR	Generic	Generic		SM0402	
7	1	TMAC3	10UF	CAP, CERAMIC,10UF,6.3V,20%,0603_X5R	Generic	Generic		SM0603	
8	1	TMAC15	1UF	CAP, CERAMIC,1UF,16V,10%,0603_X5R_PB-FR	Generic	Generic		SM0603	
9	1	C32	10UF	CAP, CERAMIC,10UF,10V,10%,0805_X5R_PB-FR	Generic	Generic		SM0805	
10	5	TMAC12;TMAC13;TMAC14;TMAC17;TMAC19	47UF	CAP, CERAMIC,47UF,6.3V,20%,1206_X5R	Generic	Generic		SM1206	
11	3	TMAC2;TMAC16;TMAC18	10uF	CAP, CERAMIC,10UF,25V,10%,1206_X7R_PB-FR	Generic	Generic		SM1206	
12	1	C10	470UF	CAP, 470UF,2.5V,20%,SM7343_LOW_ESR_PB-FR	Panasonic	EEFSX0471E4		SM7343	
13	2	C2;C3	47UF	CAP, 47UF,16V,20%,7343LOW_ESR_D_PB-FR	Panasonic	16TQC47M		SM7343	
14	1	TMAU1		TPS53355_QFN22-30A_REG	Texas Instruments	TPS53355			
15	1	TMAL1		IND_PWR_SM-0.68UH,20%,48A,XAL1010-681MEC	Coilcraft	XAL1010-681MEC			
16	1	R5	20	RESISTOR,20,0.063W,1%,0402	Generic	Generic		SM0402	
17	1	TMAR1	10K	RESISTOR,10K,0.063W,0.1%,0402_25PPM_PB-FR	Generic	Generic		SM0402	
18	1	TMAR2	15K	RESISTOR,15K,0.063W,0.1%,0402_25PPM_PB-FR	Generic	Generic		SM0402	
19	1	TMAR3	549K	RESISTOR,549K,0.063W,1%,0402	Generic	Generic		SM0402	
20	1	TMAR7	200K	RESISTOR,200K,0.063W,5%,0402	Generic	Generic		SM0402	
21	1	TMAR8	3	RESISTOR,3,0.063W,1%,0402_PB-FR	Generic	Generic		SM0402	
22	1	TMAR9	100K	RESISTOR,100K,0.063W,1%,0402_PB-FR	Generic	Generic		SM0402	
23	1	TMAR11	12.4K	RESISTOR,12.4K,0.063W,1%,0402_PB-FR	Generic	Generic		SM0402	
24	1	TMAR12	200	RESISTOR,200,0.063W,5%,0402	Generic	Generic		SM0402	
25	1	TMAR14	10.7K	RESISTOR,10.7K,0.063W,1%,0402_PB_FR	Generic	Generic		SM0402	
26	1	TMAR15	34.8K	RESISTOR,34.8K,0.063W,1%,0402_PB_FR	Generic	Generic		SM0402	
27	1	TMARF2	619K	RESISTOR,619K,0.063W,1%,0402_PB-FR	Generic	Generic		SM0402	
28	1	TMAROC	133K	RESISTOR,133K,0.063W,1%,0402_PB_FR	Generic	Generic		SM0402	
29	2	TMAR10;TMAR16	1.2	RESISTOR,1.2,0.063W,5%,0603_PB_FR	Generic	Generic		SM0603	

Do Not Stuff and Place Holder

Item	Qty	Reference	Value	Part Description	Manufacturer	Manufacturer Part Number	Alternate Part	PCB Footprint	Note
1	0	TMAC20	100PF	CAP, CERAMIC,100PF,50V,5%,0402_PB-FR				SM0402	
2	0	TMARF1	866K	RESISTOR,866K,0.063W,1%,0402_PB-FR				SM0402	
3	0	C15;C26;C27	47UF	CAP, CERAMIC,47UF,6.3V,20%,1206_X5R				SM1206	
4	0	C92	0.1UF	CAP, CERAMIC,0.1UF,16V,10%,0603				SM0603	
5	0	C61	470UF	CAP,470UF,2.5V,20%,SM7343				SM7343	
6	0	C28	47UF	CAP,47UF,16V,20%, SM7343	Panasonic	16TQC47M		SM7343	

Item	Qty	Reference	Value	Part Description	Manufacturer	Manufacturer Part Number	Alternate Part	PCB Footprint	Note
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Transient Test Circuit, Connectors and Jumpers

Item	Qty	Reference	Value	Part Description	Manufacturer	Manufacturer Part Number	Alternate Part	PCB Footprint	Note
1	2	J1;J2		CON1X3_F-ST,AMP_A-1JA,COAX_AMC_PB-FR	Generic	Generic			
2	2	R13;R47	49.9	RESISTOR,49.9,0.063W,1%,0402_PB-FR	Generic	Generic		SM0402	
3	1	R45	10K	RESISTOR,10K,0.1W,1%,0603	Generic	Generic		SM0603	
4	1	R46	0.02	RESISTOR,0.020,0.250W,1%,1206_PB-FR	Generic	Generic		SM1206	
5	5	P1;P5;P6;P16;P17		HEADER 1X2_M-ST,PB-FR	Generic	Generic			
6	2	C1;C68	0.1UF	CAP, CERAMIC,0.1UF,10V,10%,0402_X5R_PB-FR	Generic	Generic		SM0402	
7	1	Q1		N-channel, MOSFET, Powerpak	Infineon	BSC059N03S			
8	1	TMAR13	0	RESISTOR,0,0.063W,5%,0402_PBFREE	Generic	Generic		SM0402	

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